

# ATROX® 800HT7A

Hybrid Silver Sintered Electrically and Thermally Conductive Die Attach Paste

#### **DESCRIPTION**

**ATROX 800HT7A** is an ultra-low stress Hybrid Silver sintered die attach paste with high thermal conductivity designed for high power exposed pad semiconductors. **ATROX 800HT7A** has very low shrinkage during cure and low condensable organics which ensure excellent package reliability.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

### **TYPICAL PROPERTIES**

Material Properties	Method	Value	Remarks		
A. Uncured					
Chemical type		Thermosetting			
Color	Visual	Grey			
Viscosity at 25 °C at 5.0 RPM	ASTM D2196-99	17,500 cps	Brookfield Spindle 51		
Thixotropic index (0.5 RPM/5.0 RPM)	ASTM D2196-99	6.5	Brookfield Spindle 51		
Pot Life @ 23 °C (time to doubling of viscosity)	ISO 10364:1993	>24 hours	Brookfield Spindle 51		
Storage Temperature		-40 +/-5			
Shelf Life @ -40 (°C/°F)		6 months			
B. Cured					
Glass Transition (Tg)	ТМА	27°C			
Modulus at 25 °C	DMA	5.5 GPa			
Modulus at 260 °C	DMA	0.43 GPa			





# TECHNICAL DATA SHEET Semiconductor Solutions

Material Properties	Method	Value	Remarks
CTE 1 (below Tg)	TMA	49 ppm	
CTE 2 (below Tg)	ТМА	131 ppm	
Thermal Conductivity: Bulk K_eff	Laser Flash	75 W/mK 30 W/mK	
Volume Resistivity	4-Point Probe	0.00003 Ohm-cm	
% Moisture Absorption	72 hrs @ 85%RH/85 °C	< 0.75%	
Thermal Stability at 300 °C	TGA of cured sample- Ramp to 450 °C	< 0.5 %	

## DIE SHEAR STRENGTH (5.0 MM X 5.0 MM BARE SI)

Lead Frame	Cure Condition	Measuring Temperature	Value
Ag	30 min to 150 °C + 30 min at 150 °C + 200 °C for 120 min	25 °C	44 Kg
Cu	30 min to 150 °C + 30 min at 150 °C + 200 °C for 120 min	25 °C	43 Kg

### **MATERIAL APPLICATION**

ATROX 800HT7A is formulated to be applied using a time pressure pump equipped on most die bonders. The material should be consistently dispensed over time. Equipment settings need to be optimized for desired material deposition response based on model and configuration.

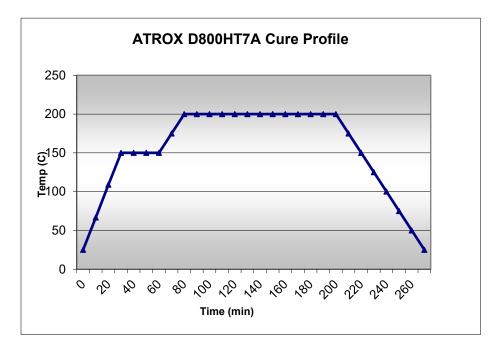




#### **CURE**

ATROX 800HT7A cures using step cure profile of 30 minutes to a 150 °C for 30 minutes followed by slow ramp of 20 minutes to 200 °C followed by soaking for a minimum of 120 minutes. It is recommended that the cure schedule includes controlled cooling cycle to minimize thermal stresses. It is possible to use higher cure temperature such as 250 °C to increase the adhesion of the die attach. However, it is recommended to optimize the cure profile for void formation especially for large die sizes

Depending on thermal mass of application cure times may vary and should be optimized by the end user.



## **RELIABILITY PERFORMANCE**

ATROX 800HT7A is recommended for excellent reliability with stable Electrical and Thermal performance during MSL and Thermal Cycling. There is no limitation on die size for metalized OR Bare Silicon die packages. However, it is recommended to consult with your local Technical Service Representative for optimizing critical parameters for specific packages.

For optimum results, it is recommended to set the Bond Line Thickness to approximately 1 mil after cure.





# CLEAN-UP

Uncured material may be cleaned from dispenser components and surfaces with a variety of solvents, including IPA, acetone, MEK, methylene chloride, etc. Always wash and dry thoroughly prior to re-use of the dispenser components. The cleaning technique should be active cleaning of the components – flush, wash or wipe, followed by a drying step to ensure a clean, dry surface. Do not soak since this can solubilize the hardener within the uncured resin and curing (very difficult to remove). Contact your equipment supplier to ensure the solvent is compatible with their components. Clean and maintain dispense valves as recommended by the equipment manufacturer.

#### **PACKAGING SIZES**

ATROX 800HT7A is available in 5 or 10 cc EFD or Musashi syringes.





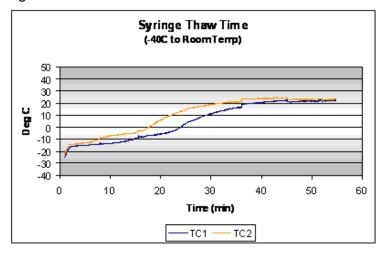
#### **SAFETY & WARNING**

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available.** 

#### **SHIPPING & STORAGE**

Material is normally shipped in insulated boxes using dry ice to ensure that the ATROX 800HT7A maintains all its properties. On receipt, it must be ensured that dry-ice remnants are present in the insulated shipping box. If there is no dry ice, or if the material is not cold, then please contact MacDermid Alpha Electronics Solutions immediately. Exposing to elevated temperatures during shipment and storage will compromise on the performance aspect of the material adversely.

It is recommended to store the syringes of material at -40 °C for a maximum shelf life of 6 months. It is recommended that the material be allowed to thaw before usage. Typical thawing times for 5cc and 10cc syringes are presented in chart below. Remove the syringe from freezer and set aside, allowing it to thaw at room temperature, until it reaches room temperature (90 minutes maximum for 30cc syringe). To prevent contamination of unused product, do not return any material to its original container.





# TECHNICAL DATA SHEET Semiconductor Solutions

#### **CONTACT INFORMATION**

# To confirm this document is the most recent version, please contact techinfo@MacDermidAlpha.com

www.macdermidalpha.com

#### North America

3950 Johns Creek Ct, Suite 300 Suwanee, GA 30024 USA 908.791.2300

#### Europe

Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400

#### Asia

14 Joo Koon Crescent, Singapore 629014 65.6430.0700

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 202, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, indirect, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "(R)" and "TM" are registered trademarks or trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.

